

SN5426, SN54LS26, SN7426, SN74LS26

QUADRUPLE 2-INPUT HIGH-VOLTAGE INTERFACE POSITIVE-NAND GATES

DECEMBER 1983—REVISED MARCH 1988

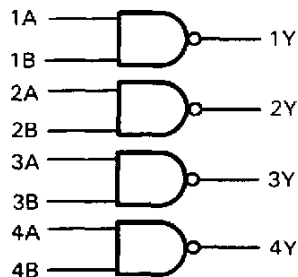
- For Driving Low-Threshold-Voltage MOS Inputs

description

These 2-input open-collector NAND gates feature high-output voltage ratings for interfacing with low-threshold-voltage MOS logic circuits or other 12-volt systems. Although the output is rated to withstand 15 volts, the V_{CC} terminal is connected to the standard 5-volt source.

The SN5426 and SN54LS26 are characterized for operation over the full military temperature range of -55°C to 125°C . The SN7426 and SN74LS26 are characterized for operation from 0°C to 70°C .

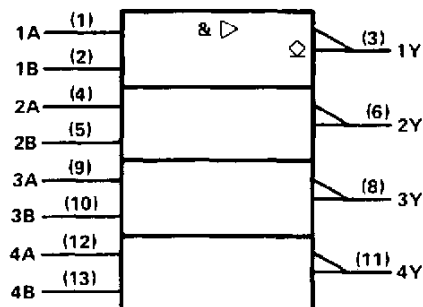
logic diagram



positive logic

$$Y = \overline{AB}$$

logic symbol†

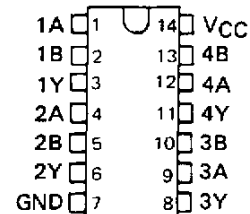


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

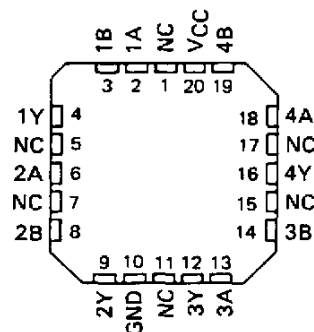
SN5426 . . . J PACKAGE
SN54LS26 . . . J OR W PACKAGE
SN7426 . . . N PACKAGE
SN74LS26 . . . D OR N PACKAGE

(TOP VIEW)



SN54LS26 . . . FK PACKAGE

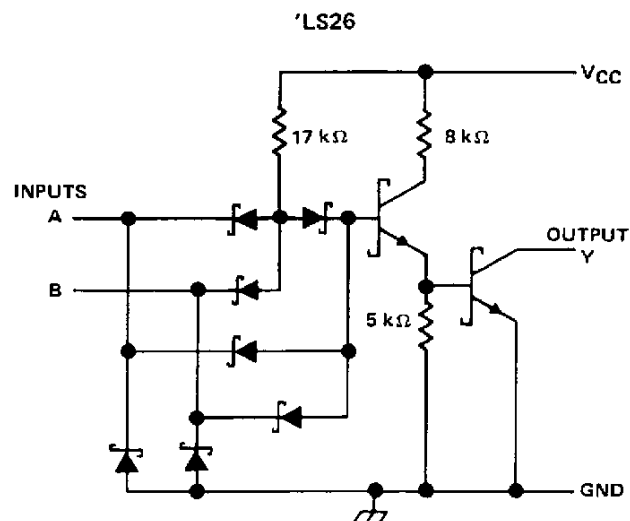
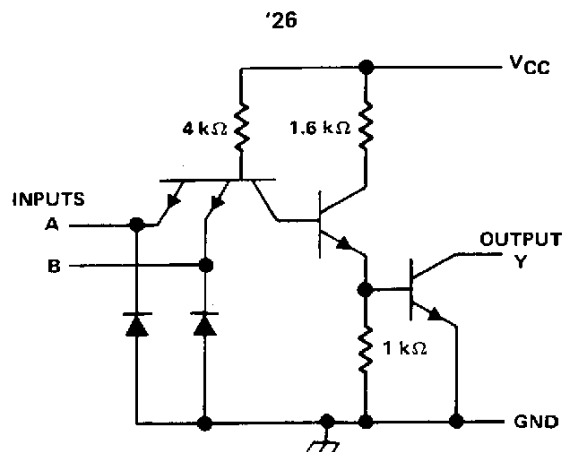
(TOP VIEW)



NC - No internal connection

SN5426, SN54LS26, SNSN7426, SN74LS26 **QUADRUPLE 2-INPUT** **HIGH-VOLTAGE INTERFACE POSITIVE-NAND GATES**

schematics



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage: '26	5.5 V
'LS26	7 V
Operating free-air temperature: SN54'	-55°C to 125°C
SN74'	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

SN54LS26, SN74LS26
QUADRUPL 2-INPUT
HIGH-VOLTAGE INTERFACE POSITIVE-NAND GATES

recommended operating conditions

	SN54LS26			SN74LS26			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH} High-level input voltage	2			2			V
V_{IL} Low-level input voltage			0.7			0.8	V
V_{OH} High-level output voltage			15			15	V
I_{OL} Low-level output current			4			8	mA
T_A Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS26			SN74LS26			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	$V_{CC} = \text{MIN}, I_I = -18 \text{ mA}$		-1.5			-1.5		V
I_{OH}	$V_{CC} = \text{MIN}, V_{IL} = \text{MAX}, V_{OH} = 12 \text{ V}$			50			50	μA
	$V_{CC} = \text{MIN}, V_{IL} = \text{MAX}, V_{OH} = 15 \text{ V}$			1			1	mA
V_{OL}	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, I_{OL} = 4 \text{ mA}$	0.25	0.4		0.25	0.4		V
	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, I_{OL} = 8 \text{ mA}$				0.35	0.5		
I_I	$V_{CC} = \text{MAX}, V_I = 7 \text{ V}$		0.1			0.1		mA
I_{IH}	$V_{CC} = \text{MAX}, V_{IH} = 2.7 \text{ V}$		20			20		μA
I_{IL}	$V_{CC} = \text{MAX}, V_{IL} = 0.4 \text{ V}$		-0.4			-0.4		mA
I_{CCH}	$V_{CC} = \text{MAX}, V_I = 0$	0.8	1.6		0.8	1.6		mA
I_{CCL}	$V_{CC} = \text{MAX}, V_I = 4.5 \text{ V}$	2.4	4.4		2.4	4.4		

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$.

switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	A or B	Y	$R_L = 2 \text{ k}\Omega, C_L = 15 \text{ pF}$		17	32	ns
t_{PHL}					15	28	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

SN5426, SN7426
QUADRUPLE 2-INPUT
HIGH-VOLTAGE INTERFACE POSITIVE-NAND GATES

recommended operating conditions

	SN5426			SN7426			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH} High-level input voltage	2			2			V
V _{IL} Low-level input voltage			0.8			0.8	V
V _{OH} High-level output voltage			15			15	V
I _{OL} Low-level output current			16			16	mA
T _A Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN5426			SN7426			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V _{IK}	V _{CC} = MIN, I _I = -12 mA			-1.5			-1.5	V
I _{OH}	V _{CC} = MIN, V _{IL} = 0.8 V, V _{OH} = 12 V						50	μA
	V _{CC} = MIN, V _{IL} = 0.7 V, V _{OH} = 12 V			50				
	V _{CC} = MIN, V _{IL} = 0.8 V, V _{OH} = 15 V						1	mA
	V _{CC} = MIN, V _{IL} = 0.7 V, V _{OH} = 15 V			1				
V _{OL}	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 16 mA			0.4			0.4	V
I _I	V _{CC} = MAX, V _I = 5.5 V			1			1	mA
I _{IH}	V _{CC} = MAX, V _I = 2.4 V			40			40	μA
I _{IL}	V _{CC} = MAX, V _I = 0.4 V			-1.6			-1.6	mA
I _{CCCH}	V _{CC} = MAX, V _I = 0			4			4	mA
I _{CCCL}	V _{CC} = MAX, V _I = 4.5 V			12			12	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡All typical values are at V_{CC} = 5 V, T_A = 25°C.

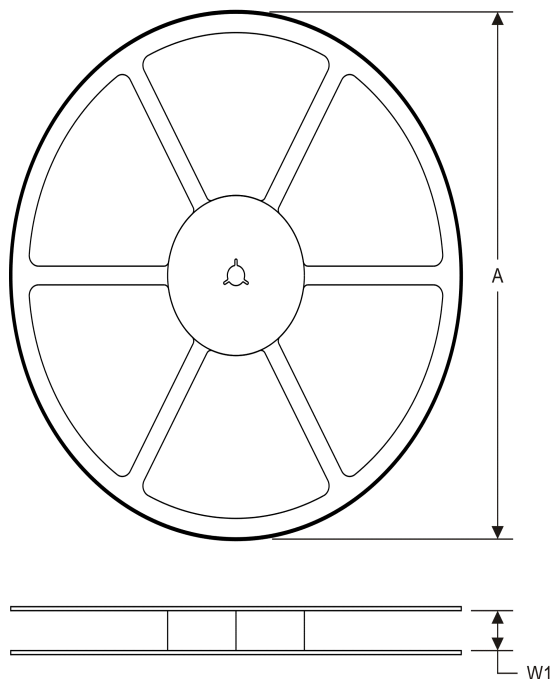
switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	A or B	Y	R _L = 1 kΩ, C _L = 15 pF		16	24	ns
t _{PHL}					11	17	ns

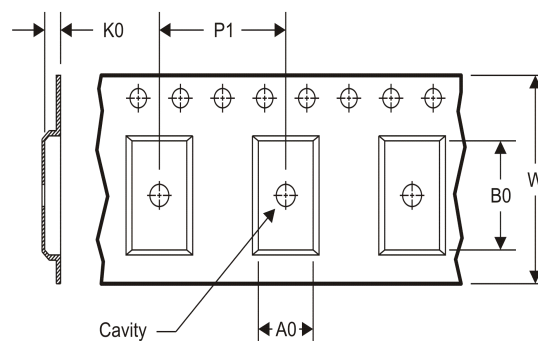
NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



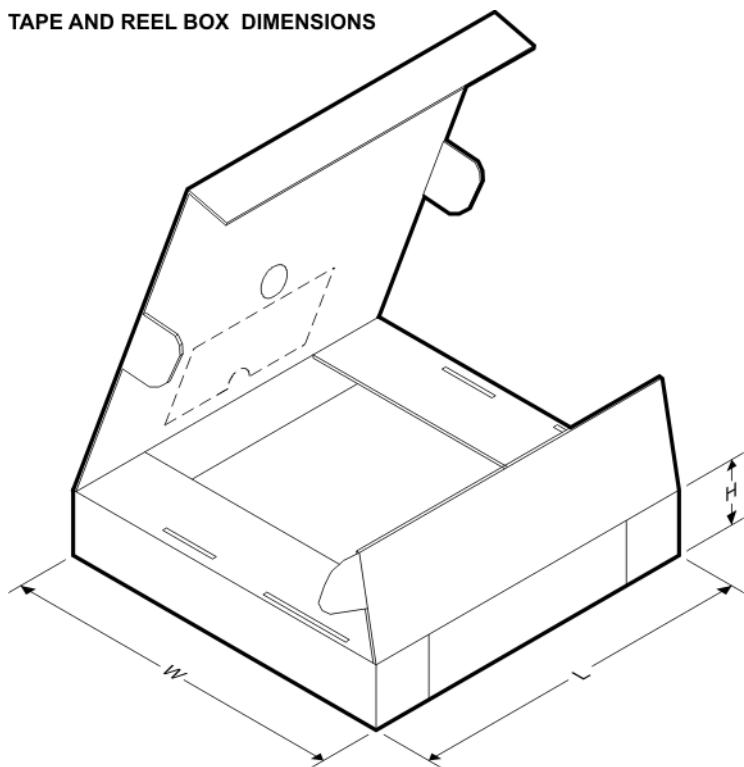
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS26DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS26DR	SOIC	D	14	2500	367.0	367.0	38.0

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